

## LTM4616 144LD 15mm X 15mm X 2.82mm (TABLE OF MATERIAL DECLARATION)

***The LTM4616 is RoHS compliant per EU RoHS Directive 2003/95/EC.***

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1650	Barium Compounds	7727-43-7	0.0025	1.50
				Filler Substances (Silica Crystalline)	non-disclosure	0.0659	39.91
				Copper Metal	7440-50-8	0.0924	56.00
				Copper Compounds	1328-53-6	0.0000	0.02
				Ecotoxic substances	7439-92-1	0.0000	0.00
				Gold metal or alloy	7440-57-5	0.0008	0.46
				Nickel	7440-02-0	0.0035	2.10
2	Solder Paste	Alloy	0.0230	Zinc	7440-66-6	0.0000	0.01
				Sn	7440-31-5	0.0218	95.00
3	Passive/Active Components		0.4688	Sb	7440-36-0	0.0011	5.00
				Iron Powder (Fe)	7439-89-6	0.2119	45.21
				Copper (Cu)	7440-50-8	0.1164	24.83
				Nickel (Ni)	7440-02-0	0.0009	0.18
				Tin (Sn)	7440-31-5	0.0005	0.10
4	Active Ics	Silicon	0.0124	Ceramic (Ba) Compounds	non-disclosure	0.1391	29.67
5	Wire	Gold	0.0032	Silicon	7440-21-3	0.0124	100.00
6	Encapsulation	Epoxy Resin	1.1051	Au	7440-57-5	0.0032	99.99
				Fused Silica	60676-86-0	0.8531	77.20
				Epoxy Resin	non-disclosure	0.0984	8.90
				Phenol Resin	non-disclosure	0.0984	8.90
				Crytalline Silica	14808-60-7	0.0332	3.00
				Carbon Black	1333-86-4	0.0055	0.50
				Metal Hydroxide	non-disclosure	0.0166	1.50
Total Package Weight			1.7774				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts